

RoHS Compliance Material Declaration Report

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|-----------------|--|----------------------|--|
| Company: | Pericom | Address: | 3545 North First Street, San Jose, CA, 95134 |
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| Part Detail | | | | | |
|---------------------|--------------------------------|---------------------|------------------------|--------------------------|--|
| Pericom Part Number | Manufacturer part description | Package Type | Number of Pin/Terminal | Component overall weight | |
| PS399CSEE | Precision Diff 4-CH,17V Analog | SOIC (150mil width) | 16 | 0.14615 | |

| RoHS Compliance | | |
|---|----------------------------------|------------------------------------|
| Is Part compliant to EU RoHS Directive? <i>[1] Yes, [2] Yes with tech exemption* [3] Yes but needs product application exemption* [4] No</i> | RoHS tech exemption [2] details. | Date Component was RoHS Compliant. |
| Yes | N/A | Since Inception |

| Content of RoHS restricted materials (g) | | | | | | |
|--|---------|---------|---------------------|--------------------------------|--------------------------------------|---|
| Lead | Cadmium | Mercury | Hexavalent Chromium | Polybrominated biphenyls (PBB) | Polybrominated Diphenylethers (PBDE) | RoHS restricted substance added intentionally? For what reason? |
| 0 | 0 | 0 | 0 | 0 | 0 | N/A |

| Component Soldering Process | | | | | | |
|---|-------------------------------|---|--|-------------------------------------|--------------------------|-----------------------------|
| Interconnect Composition, (Metallurgy of the lead/terminal) | JEDEC JEDS97 Pb-free Category | Compatible with a 260C 10s Pb-Free assembly process | Backward compatible with SnPb assembly | Maximum Processing Temperature (°C) | Max Temperature Duration | Max Number of reflow cycles |
| Sn | e3 | Yes | Yes | 260 | 40 | 3 |

| Plastics (if applicable) | | | |
|--------------------------|--|-----------------|--------------------------------|
| Oxygen Index | Type of plastic material used in the component | Fire: UL Rating | MSL Level (per JEDEC STD 020C) |
| >28% | Epoxy Resin | V-0 | 1 |

| Tin (Sn) Plating (If Applicable) | | | | | |
|---|----------------------------|---|--------------------------|---|------------------------------|
| Tin (Sn) Plating – is it Matte (M) or Bright (B)? | Tin (Sn) Plating Thickness | Tin (Sn) plating is there a Nickel (Ni) Barrier? - Yes / No | Nickel Barrier Thickness | If no Nickel barrier is the tin (Sn) termination finish heat treated? | Performed Tin Whisker Test ? |
| M | 7 to 20 um | No | N/A | Yes, 150C / 1 Hr | Yes |

| Bismuth (Bi) |
|--------------------------------------|
| Bismuth (Bi) Content (if applicable) |
| 0 |